



Material Content Data Sheet



Sales Product Name		IPD26N06S2L-35		Issued		29. August 2013			
MA#		MA000260982							
Package		PG-TO252-3-11		Weight*		369.70 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.550	0.42	0.42	4194	4194	
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		634		
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190		
	non noble metal	copper	7440-50-8	234.187	63.36	63.44	633457	634281	
wire	non noble metal	aluminium	7429-90-5	0.958	0.26	0.26	2590	2590	
encapsulation	organic material	carbon black	1333-86-4	1.273	0.34		3442		
	plastics	epoxy resin	-	22.272	6.02		60243		
	inorganic material	silicondioxide	60676-86-0	103.722	28.06	34.42	280559	344244	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10117	10117	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		246		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	247	
solder	noble metal	silver	7440-22-4	0.040	0.01		108		
	non noble metal	tin	7440-31-5	0.032	0.01		87		
	non noble metal	lead	7439-92-1	1.528	0.41	0.43	4132	4327	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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